

DATASHEET

Lamp 7383/BAC3-ANQA/MS



Features

- Popular T-1 3/4 round package.
- Choice of various viewing angles.
- Available on tape and reel.
- Reliable and robust.
- The product itself will remain within RoHS compliant version.

Descriptions

- The series is specially designed for applications requiring higher brightness.
- The LED lamps are available with different colors, intensities, epoxy colors, etc.

Applications

- Color Graphic Signs
- Message boards
- Variable message signs (VMS)
- Commercial outdoor advertising



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Blue	Water Clear

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V _R	5	V	
Forward Current	I _F	30	mA	
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA	
Power Dissipation	Pd	120	mW	
Operating Temperature	Topr	-40 ~ +85	$^{\circ}$	
Storage Temperature	Tstg	-40 ~ +100	$^{\circ}$	
ESD	ESD _{HBM}	1K	V	
Soldering Temperature	Tsol	260 °C for 5 sec.		

Electro-Optical Characteristics (Ta=25°C)

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Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Radiometric Intensity	lv	2250	2850	4500	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}		30		deg	I _F =20mA
Peak Wavelength	λр		468		nm	I _F =20mA
Dominant Wavelength	λd	465	470	475	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		26		nm	I _F =20mA
Forward Voltage	V _F	2.8		3.6	V	I _F =20mA
Reverse Current	I _R			50	μΑ	V _R =5V



Bin Range of Radiometric Intensity

Bin Code	Min.	Max.	Unit	Condition
N	2250	2850		
Р	2850	3600	mcd	$I_F = 20 \text{mA}$
Q	3600	4500		

Note:

Measurement Uncertainty of Radiometric Intensity: ±10%

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
1	465	470		I 00 A
2	470	475	nm	$I_F = 20 \text{mA}$

Note:

Measurement Uncertainty of Dominant Wavelength ±1.0nm

Bin Range of Forward Voltage

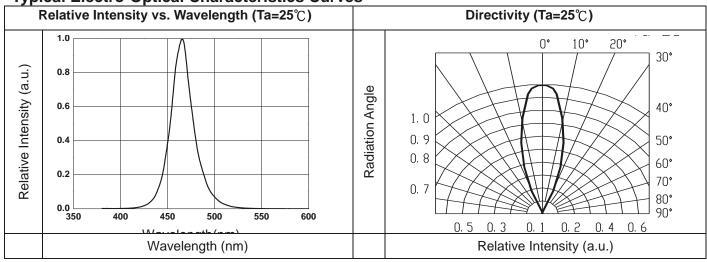
Bin Code	Min.	Max.	Unit	Condition
0	2.8	3.0		
1	3.0	3.2		I 00 A
2	3.2	3.4	\ \ \ \	$I_F = 20 \text{mA}$
3	3.4	3.6		

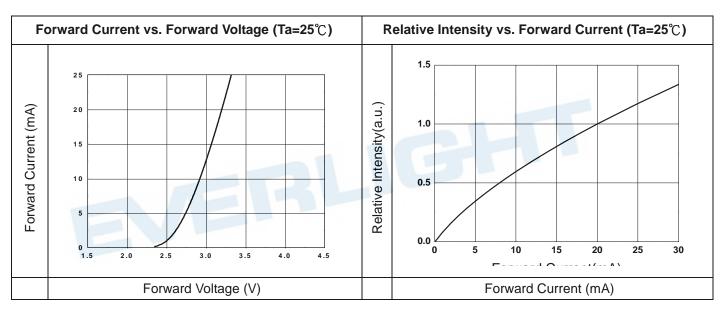
Note:

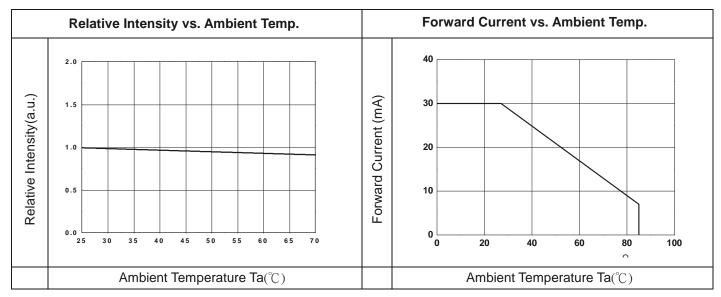
Tolerance of Forward Voltage: ±0.1V



Typical Electro-Optical Characteristics Curves

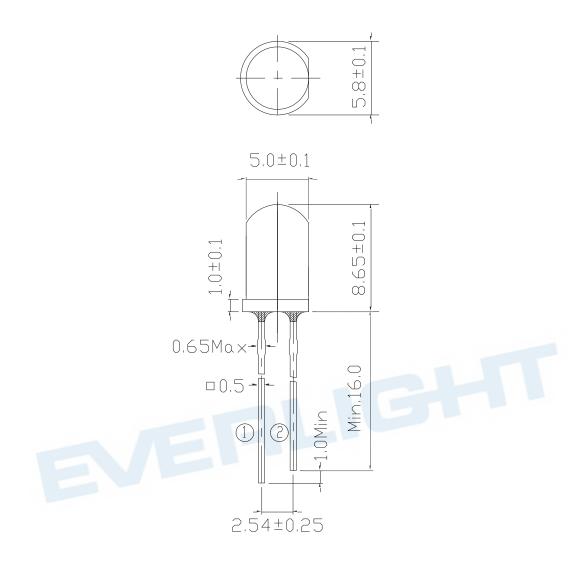








Package Dimension





Note:

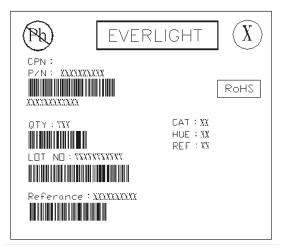
Other dimensions are in millimeters, tolerance is 0.25mm except being specified.

'Protruded resin under flange is 1.5mm Max LED.

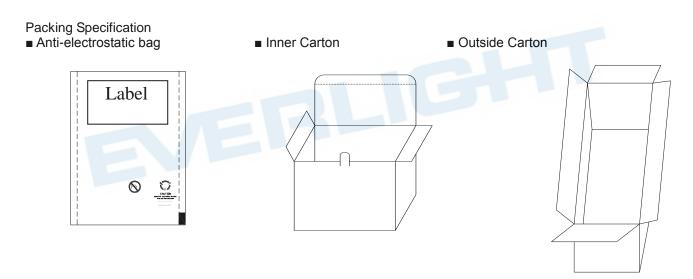


Moisture Resistant Packing Materials

Label Explanation



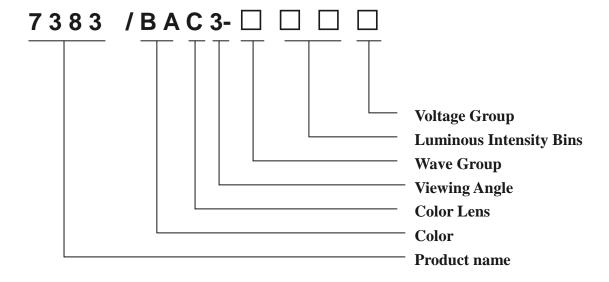
- CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- · CAT: Ranks of Luminous Intensity and Forward Voltage
- · HUE: Rank of Dominant Wavelength
- · REF: Reference
- · LOT No: Lot Number



- Packing Quantity
- 1. Min 200pcs to Max 500 PCS/1 Bag, 5 Bags/1 Inner Carton.
- 2. 10 Inner Cartons/1 Outside Carton



Production Designation



Notes

1. Lead Forming

- During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- Lead forming should be done before soldering.
- Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

2. Storage

- The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Everlight and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

3. Soldering

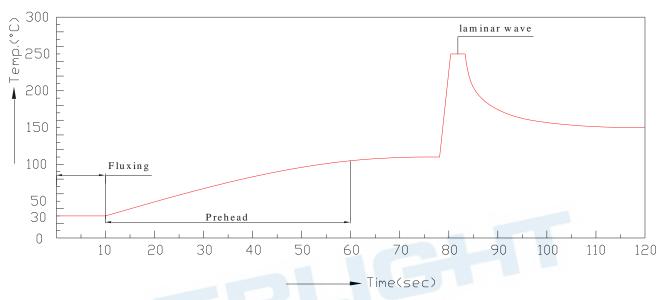
■ Careful attention should be paid during soldering. When soldering, leave more then 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.



Recommended soldering conditions:

Hand Soldering		DIP Soldering		
Town at tip of iron	300°C Max. (30W	Preheat temp.	100°C Max. (60 sec	
Temp. at tip of iron Max.)		Freneat temp.	Max.)	
Soldering time	oldering time 3 sec Max.		260 Max., 5 sec Max	
Distance	3mm Min.(From	Distance	3mm Min. (From	
solder joint to			solder joint to epoxy	
epoxy bulb)			bulb)	

■ Recommended soldering profile



- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- Dip and hand soldering should not be done more than one time
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or handsoldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

4. Cleaning

- When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
- Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic



cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition.

Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED

5. Heat Management

- Heat management of LEDs must be taken into consideration during the design stage of LED application. The current should be de-rated appropriately by referring to the de-rating curve found in each product specification.
- The temperature surrounding the LED in the application should be controlled. Please refer to the data sheet de-rating curve.

6. ESD (Electrostatic Discharge)

- Electrostatic discharge (ESD) or surge current (EOS) can damage LEDs.
- An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling LEDs.
- All devices, equipment and machinery must be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing.

7. Other

- Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply

with the absolute maximum ratings and the instructions included in these specification sheets.

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